



TE Internal #: 2-2013289-2  
 Double Data Rate (DDR) 3, Stack Height 5.2 mm [.205 in], Right Angle Module Orientation, 204 Position, .6 mm [.024 in] Centerline, SO DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 3**  
 Stack Height: **5.2 mm [.205 in]**  
 Module Orientation: **Right Angle**  
 Number of Positions: **204**  
 Centerline (Pitch): **.6 mm [.024 in]**

### Features

#### Product Type Features

DRAM Type	Double Data Rate (DDR) 3
Connector & Contact Terminates To	Printed Circuit Board
Connector System	Cable-to-Board

#### Dimensions

Stack Height	5.2 mm[.205 in]
Row-to-Row Spacing	8.2 mm[.322 in]

#### Configuration Features

Module Orientation	Right Angle
Number of Positions	204
Number of Bays	2
Number of Keys	1
Number of Rows	2

#### Housing Features

Centerline (Pitch)	.6 mm[.024 in]
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Housing Material	High Temperature Thermoplastic
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Housing Color	Black
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### Body Features

Connector Profile	Standard
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Latch Plating Material	Tin
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Latch Material	Stainless Steel
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Module Key Type	SGRAM
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Ejector Type	Locking
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Ejector Location	Both Ends
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### Contact Features

Contact Mating Area Plating Material	Gold
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Contact Mating Area Plating Material Thickness	.254 $\mu\text{m}$ [10 $\mu\text{in}$ ]
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Contact Current Rating (Max)	.5 A
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Memory Socket Type	Memory Card
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Contact Base Material	Copper Alloy
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PCB Contact Termination Area Plating Material	Gold
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### Packaging Features

Packaging Method	Emboss on Reel
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Packaging Quantity	200
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### Operation/Application

Circuit Application	Power
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### Usage Conditions

Operating Temperature Range	-55 – 85 $^{\circ}\text{C}$ [-67 – 185 $^{\circ}\text{F}$ ]
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### Other

EU RoHS Compliance	Compliant
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EU ELV Compliance	Compliant
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### Electrical Characteristics

DRAM Voltage	1.5 V
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### Signal Characteristics

SGRAM Voltage	1.5 V
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### Termination Features



Insertion Style	Cam-In
Termination Method to PCB	Surface Mount

### Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention Type	Solder Peg
Mating Alignment Type	Standard Keying
PCB Mount Retention	With

### Industry Standards

UL Flammability Rating	UL 94V-0
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

### Compatible Parts



### Customers Also Bought



### Documents

#### Product Drawings

[EMBOSS TAPE DDR3 204P 5.2H STD Au 0.25](#)

English

#### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_2-2013289-2\\_B.2d\\_dxf.zip](#)

English

[3D PDF](#)



3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2-2013289-2\\_B.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2-2013289-2\\_B.3d\\_stp.zip](#)

English

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### Datasheets & Catalog Pages

[DDR3 DIMM Sockets Flyer 6-1773454-7 05/09](#)

English

[6-1773457-3\\_DDR3\\_DIMM\\_SOCKETS](#)

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### Product Specifications

[Product Specification](#)

English